

TAPE SUPPORTED MEMORY CARD LEADFRAME STRUCTURE

ABSTRACT OF THE INVENTION

[0053] A method of fabricating a memory card. The method comprises the initial step of providing a leadframe which has a dambar and a plurality of contacts, each of the contacts being attached to the dambar by at least one tie bar. A layer of tape is applied to the leadframe such that the tape covers at least portions of the top contact surfaces of the contacts, at least portions of the top tie bar surfaces of the tie bars, and at least a portion of the top dambar surface of the dambar. Thereafter, the tie bars are removed from the leadframe. At least one semiconductor die is then electrically connected to the leadframe, with a body thereafter being formed on the leadframe such that the semiconductor die and the tape are covered by the body and the bottom contact surfaces are exposed in an exterior surface thereof.